Messrs. Digi-Key

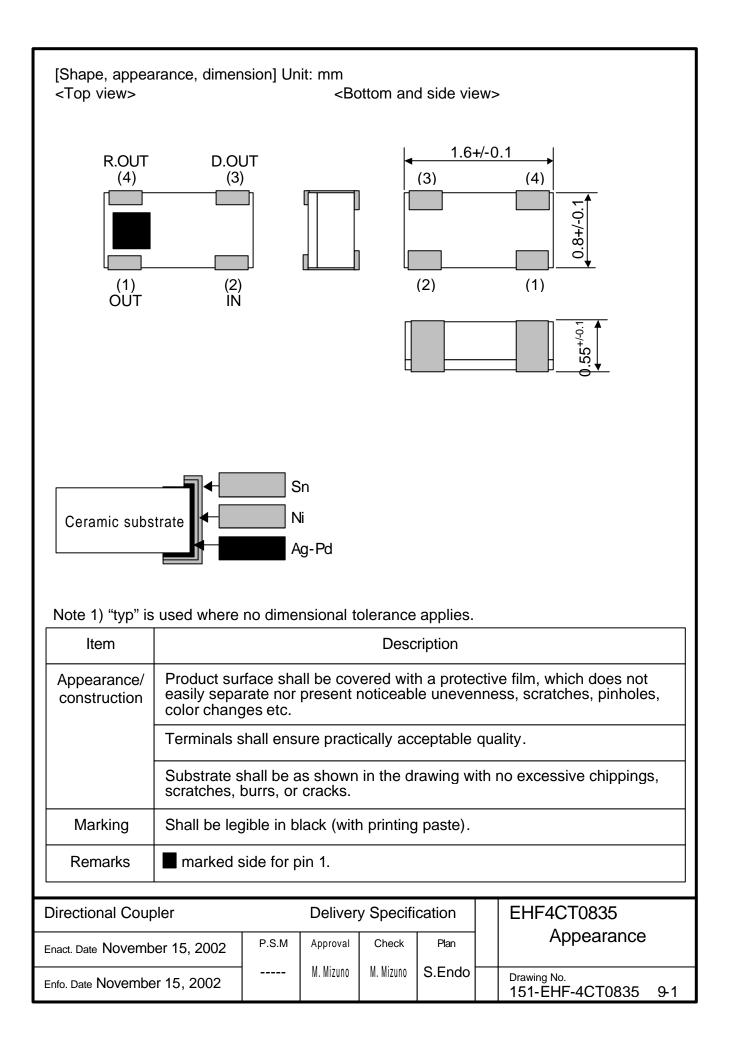
Issue No.: PC-02-047Date of issue : November 15, 2002Classification :■ New □ Change □ Renewal

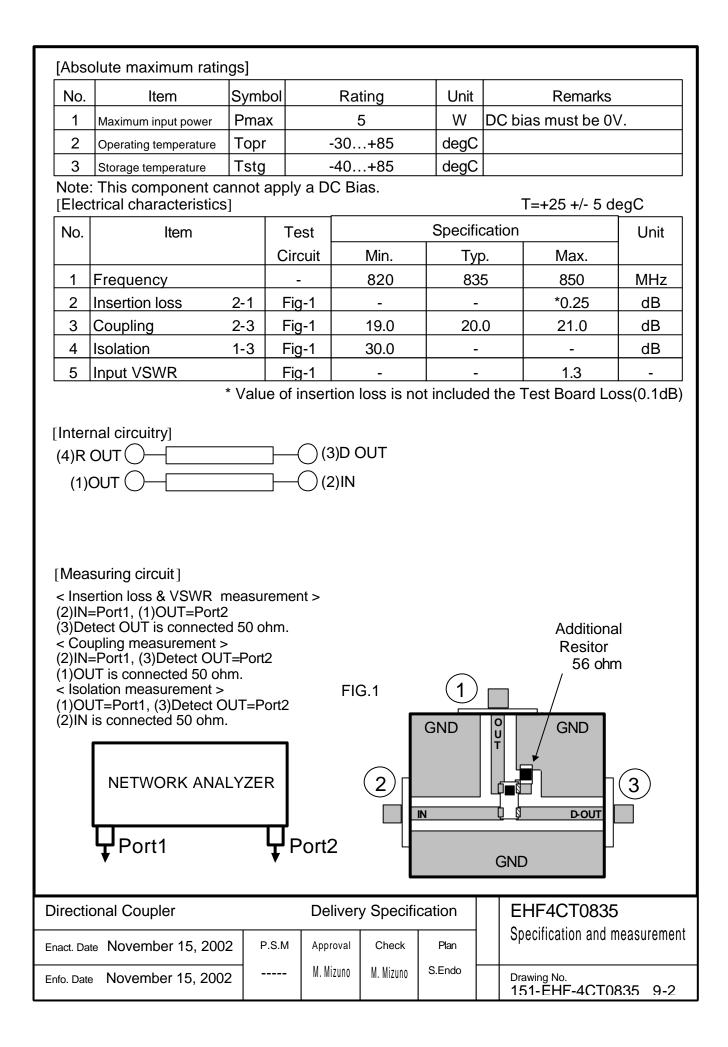
Delivery Specification

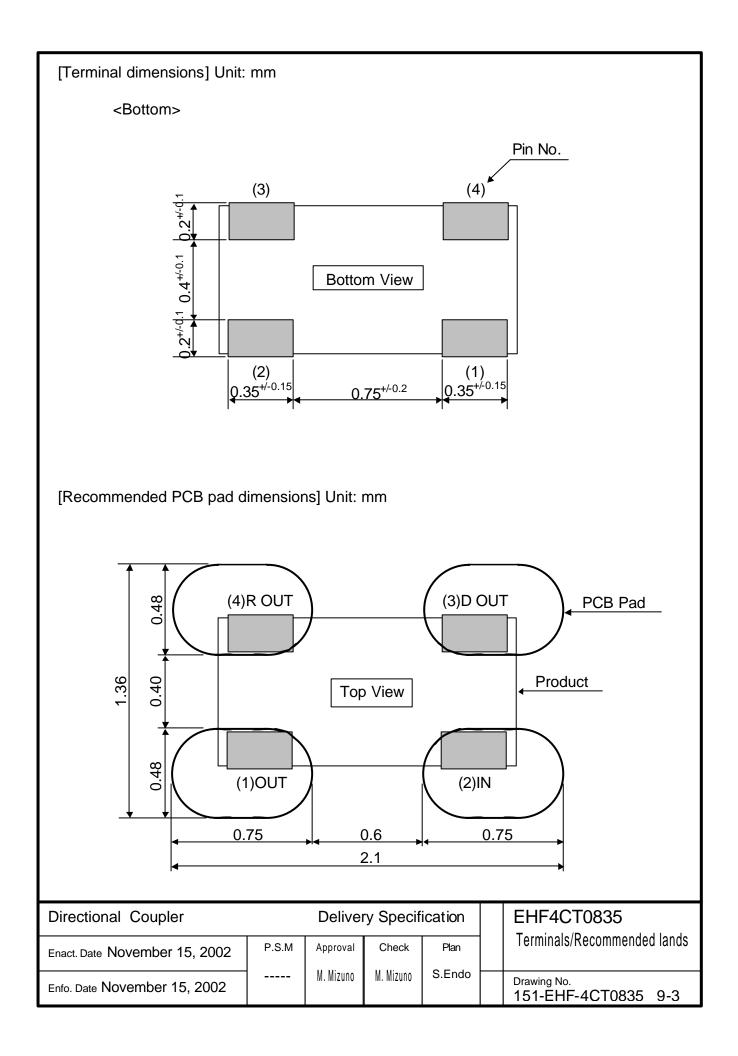
| Product Description | : Directional Coupler |
|------------------------|---|
| Product Part Number | : EHF4CT0835 |
| Classification of Spec | : Individual Product Specification |
| Applications | : Cellular phone |
| | For other applications, contact the undersigned in advance. |
| Term of Validity | : November 14, 2007 from the date of issue. |

| CUSTOMER USE ONLY | Receipt Record#: | |
|---|------------------|--|
| This was certainly received by us. 1(one) copy is being returned to you. | Date of receipt: | |
| | Received by: | |
| | Title: Dept.: | |

| Matsushita Electronic Components Co., Ltd. | | |
|---|---------------|--------------------------|
| Network Device Company | Prepared by | : S.Endo |
| Module Strategic Business Unit | Checked by | : M. Mizuno |
| Engineering Group HFD Team | | |
| 992-1 Aiba Ohno-cho Ibi-gun Gifu 501-0598 JAPAN | Authorized by | : M. Mizuno |
| Tel: +81-0585-36-2322 | Title | : Manager of Engineering |
| Fax: +81-0585-36-2344 | | . Manager of Engineering |







| [Quality characteristic | s] | | | | | | |
|---|---|--|--|--|--|--|--|
| Test item | Test condition | Judgment criteria | | | | | |
| High temperature | +85degC, 1000h | No abnormality shall be observed in | | | | | |
| Low temperature | -40degC, 1000h | appearance or electrical characteristics. | | | | | |
| High-temperature high-humidity storage | +60degC, 90%RH, 1000h | | | | | | |
| Pressure Pot | +121degC, 99%RH, 2.026x10 ⁵ Pa, 100h | characteristics. | | | | | |
| Temperature cycling | -40…+85degC, Each 30 min., 200cy | | | | | | |
| Vibration | 10500Hz, 10G, in each direction of XYZ, 2h30min. | | | | | | |
| Impact | 100G, 6mS, Half sinusoidal wave, in each direction of XYZ, 3 times | | | | | | |
| Shock (Drop) | 1.8m, 6 facesx6cy(36 times with 100g Dummy Load) | | | | | | |
| Electro static discharge | 200pF, 0 ohm, +/-200V, Each 5 times | | | | | | |
| Soldering heat resistance | Manual hot gas: 260+/-10degC, 30 sec., 2 times | Over 90% of the terminal | | | | | |
| | Soldering iron: 260+/-10degC, 3 sec., 2 times | surface shall be covered with solder. | | | | | |
| | Reflow: 260degC peak, 2 times | | | | | | |
| Solder ability | Solder bath: 235+/-5degC, 2 sec. | Over 95% of the terminal | | | | | |
| | Reflow: 230degC | surface shall be covered with solder. | | | | | |
| Board warping | Assemble this component on a PC board with 0.8mm thickness using the recommended soldering condition shown below, and apply a bending force of 3mm warping at a rate of 1mm/sec. 5 seconds and 5 times. t=0.8mm | There should not be any cracks in the component or solder joints, no abnormality in electrical characteristics. | | | | | |
| Terminal removal | Solder a component on a PC board using the recommended then press the component sideways at 1mm/sec. Destruction lir | | | | | | |
| Seating plane co-planarity | Within 0.1mm | | | | | | |
| < Recommended sold Diagram1 Shown b degC 250 230 200 170 140 | below is a recommended reflow soldering conditio | | | | | | |
| <u>30~60 sec.</u> <u>60~180 sec.</u> <u>Time</u> | | | | | | | |
| Directional Coupler | Delivery Specification EHF | 4CT0835 | | | | | |
| Enact. Date November 15, 2002 P.S.M Approval Check Plan Quality Characteristic M. Mizuno M. Mizuno S.Endo Drawing No. | | | | | | | |
| Enfo. Date November 15, 20 | ^{g No.} EHF-4CT0835 9-4 | | | | | | |

[Cautions for use]

| (1) Operating a product over the maximum rating for even a moment may result in a |
|---|
| product failure or breakage. Never use a product in such a condition that it may |
| cause a safety problem. |

- (2) Opening or short-circuiting the product terminals or inserting a product in the reverse orientation while power is being supplied may cause a breakage. Always avoid such circumstances.
- (3) Operations in a corrosive gas atmosphere or improper environments such as hightemperature, high-humidity or dewy conditions may lead to product performance deterioration, a breakage, a change in appearance etc. Please avoid such conditions, as they are unsafe.
- (4) Always ground the soldering iron or soldering bath used for assembly operation to avoid any excessive voltage applied to a product.
- (5) After soldering with solder bridges, incomplete soldering or in the reverse orientation, supplying power may result in a product breakage. Please confirm the soldered condition before supplying power to the product.
- (6) Excessive stress on the terminals may cause a contact failure or performance deterioration. Please use caution.
- (7) Please provide a fail-safe provision in the product you design by taking any failure of our product into consideration.
- (8) This product does not include a DC-cutting device. Application of a DC Current may cause product deterioration or breakage.
 - * If any question arises about the safety of this product, please contact us immediately with a request for an engineering examination.

[Remarks]

- *1: All of the materials used in this product are those listed as the existing chemical substances based on the "Law for examination and regulation of manufacture of chemical substances".
- *2: The production process of this product does not use any ozone-depleting chemicals (OZC) regulated by the Montreal Protocol.
- *3: Validity of this specification is 5 years from the date of issue, but the validity is considered on going unless any changes are made.

| Directional Coupler | | Delivery Specification | | | | EHF4CT0835 | |
|-------------------------------|-------|------------------------|-----------|--------|--|------------------------------------|--|
| Enact. Date November 15, 2002 | P.S.M | Approval | Check | Plan | | Cautions | |
| Enfo. Date November 15, 2002 | | M. Mizuno | M. Mizuno | S.Endo | | Drawing No. 151-EHF-4CT0835 9-5 | |

[Packaging materials] 1. Materials 1)

- Embossed carrier tape (Refer to the attachment)
 Top tape: Anti-static

- 3) Packaging box (Refer to the attachment)4) Packaging tape, carrier-securing adhesive tape
- 2. Specification

| | | 1 | | | | | | ı |
|---|-------------------------------------|-------------|-----------------------|--|------------------|--|----------------------------------|--|
| No. | Item | Condition | | | | | | Remarks |
| 1 | Reel outer diameter | Refer to | the att | | | | | |
| 2 | Reel inner diameter | Refer to | the att | | | | | |
| 3 | Reel inner width | Refer to | the att | | | | | |
| 4 | Quantity in a reel | 4000 pie | eces/re | el | | | | |
| 5 | Taping direction | | | | | | ling direction ngs facing up) | |
| 6 | Top tape attachment position | | e attachm edge mus | | | 5.5mm Emb | tape | Tape breaks force. Min. 10N Top cover tape strength. Min. 10N Tape peel force. 0.11.0N Tape peel angle. 165180degree Reel weight. Max 1500g |
| 7 | Label attachment position | | | Indicated Item Pat No., Lot No. Quantity, Maker Country of Origin | | | | |
| 8 | Tape leader part and tape ending | Leader part | | | | | | |
| | part | 200- | art Prod | | 1 00~150mm, 2 | d carrier 25~38 pieces unloaded part | Top tape t) 300~ 400mm | |
| 9 Missing products No missing products shall be allowed. | | | | | | | | |
| 10Packaged quantity in a box21 reels/box (Max)84000 pieces/box(Max) | | | | | | | | |
| Dire | | | | | | CT0835 ging specification 1 | | |
| Enact. Date November 15, 2002 | | | | | | | | |
| Enfo. Date November 15, 2002 | | | | | | | | |

